

Day : Monday
Date: 3/22/2004

Time: 15:07:23

PALM INTRANET**Inventor Name Search Result**

Your Search was:

Last Name = TAKEZAWA

First Name = HIROAKI

Application#	Patent#	Status	Date Filed	Title	Inventor Name 26
10613042 <i>KOPEC</i>	Not Issued	030	07/07/2003	CONDUCTIVE ADHESIVE AGENT, PACKAGING STRUCTURE, AND METHOD FOR MANUFACTURING THE SAME STRUCTURE	TAKEZAWA, HIROAKI
10409400	Not Issued	092	04/07/2003	MOUNTING STRUCTURE FOR AN ELECTRONIC COMPONENT AND METHOD FOR PRODUCING THE SAME	TAKEZAWA, HIROAKI
10309597	6675474	150	12/03/2002	ELECTRONIC COMPONENT MOUNTED MEMBER AND REPAIR METHOD THEREOF	TAKEZAWA, HIROAKI
10309596 <i>KOPEC</i>	Not Issued <i>(3)</i>	092	12/03/2002	CONDUCTIVE ADHESIVE AND CONNECTION STRUCTURE USING THE SAME	TAKEZAWA, HIROAKI
10309426	6666994	150	12/03/2002	CONDUCTIVE ADHESIVE AND PACKAGING STRUCTURE USING THE SAME	TAKEZAWA, HIROAKI
10030235	Not Issued	030	03/26/2002	CONDUCTIVE ADHESIVE, APPARATUS FOR MOUNTING ELECTRONIC COMPONENT, AND METHOD FOR MOUNTING THE SAME	TAKEZAWA, HIROAKI
09965768	6569512	150	09/27/2001	MOUNTING STRUCTURE FOR AN ELECTRONIC COMPONENT AND METHOD FOR PRODUCING THE SAME	TAKEZAWA, HIROAKI
09947353 <i>KOPEC</i> <i>parent</i>	6620345	150	09/07/2001	CONDUCTIVE ADHESIVE AGENT, PACKAGING STRUCTURE, AND METHOD	TAKEZAWA, HIROAKI

				FOR MANUFACTURING THE SAME STRUCTURE	
09898721	6524721	150	07/03/2001	CONDUCTIVE ADHESIVE AND PACKAGING STRUCTURE USING THE SAME	TAKEZAWA, HIROAKI
09893106	6512183	150	06/27/2001	ELECTRONIC COMPONENT HAVING A CIRCUIT BOARD AND A THERMOPLASTIC INSULATING ADHESIVE INTERMEDIATE LAYER	TAKEZAWA, HIROAKI
09889523	6510059	150	07/18/2001	CONDUCTIVE RESIN, ELECTRONIC MODULE USING CONDUCTIVE RESIN, AND METHOD OF MANUFACTURING ELECTRONIC MODULE	TAKEZAWA, HIROAKI
09873461	6694613	150	06/05/2001	A METHOD FOR PRODUCING A PRINTED CIRCUIT BOARD HAVING PROJECTION ELECTRODES	TAKEZAWA, HIROAKI
09751621 <i>KOPEL</i>	6521144	150	12/29/2000	CONDUCTIVE ADHESIVE AND CONNECTION STRUCTURE USING THE SAME	TAKEZAWA, HIROAKI
09747976	Not Issued	041	12/27/2000	ELECTRONIC PART, AN ELECTRONIC PART MOUNTING ELEMENT AND AN PROCESS FOR MANUFACTURING SUCH THE ARTICLES	TAKEZAWA, HIROAKI
09703286	Not Issued	061	11/01/2000	METHOD OF MAKING AN ORGANIC ULTRA-THIN FILM	TAKEZAWA, HIROAKI
09703284	Not Issued	120	11/01/2000	METHOD OF MAKING AN ORGANIC ULTRA-THIN FILM	TAKEZAWA, HIROAKI
09554502	6465082	150	05/16/2000	STRESS RELAXATION ELECTRONIC PART, STRESS RELAXATION WIRING BOARD, AND STRESS RELAXATION ELECTRONIC PART MOUNTED BODY	TAKEZAWA, HIROAKI
09547922	6429382	150	04/11/2000	ELECTRICAL MOUNTING STRUCTURE HAVING AN ELUTION PREVENTIVE FILM	TAKEZAWA, HIROAKI

09519984	6376051	150	03/07/2000	MOUNTING STRUCTURE FOR AN ELECTRONIC COMPONENT AND METHOD FOR PRODUCING THE SAME	TAKEZAWA, HIROAKI
09125622	6495247	150	08/21/1998	FUNCTIONAL MEMBER HAVING MOLECULAR LAYER ON ITS SURFACE AND METHOD OF PRODUCING THE SAME	TAKEZAWA, HIROAKI
09107319	6207550	150	06/30/1998	METHOD FOR MOUNTING A SEMICONDUCTOR DEVICE ON A MULTILAYER SUBSTRATE	TAKEZAWA, HIROAKI
09106302	6300576	150	06/29/1998	PRINTED-CIRCUIT BOARD HAVING PROJECTION ELECTRODES AND METHOD FOR PRODUCING THE SAME	TAKEZAWA, HIROAKI
09056774	6488869	150	04/08/1998	CONDUCTIVE PASTE, ITS MANUFACTURING METHOD, AND PRINTED WIRING BOARD USING THE SAME	TAKEZAWA, HIROAKI
08992049	Not Issued	061	12/17/1997	ORGANIC ULTRA-THIN FILM AND METHOD FOR MAKING THE SAME	TAKEZAWA, HIROAKI
08980749	6203919	150	12/01/1997	INSULATING FILM AND METHOD FOR PREPARING THE SAME	TAKEZAWA, HIROAKI
08650747	5817190	150	05/20/1996	FLUX FOR SOFT SOLDERING	TAKEZAWA, HIROAKI

Inventor Search Completed: No Records to Display.

Search Another: Inventor	Last Name	First Name
	TAKEZAWA	HIROAKI
		<input type="button" value="Search"/>

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | Home page